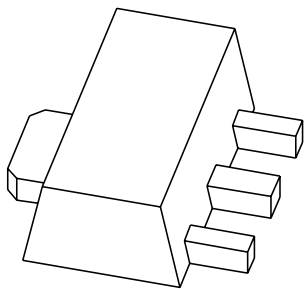


DATA SHEET



BST50; BST51; BST52 NPN Darlington transistors

Product specification
Supersedes data of 2001 Feb 20

2004 Dec 09

NPN Darlingtons

BST50; BST51; BST52

FEATURES

- High current (max. 0.5 A)
- Low voltage (max. 80 V)
- Integrated diode and resistor.

APPLICATIONS

- Industrial switching applications such as:
 - Print hammer
 - Solenoid
 - Relay and lamp driving.

DESCRIPTION

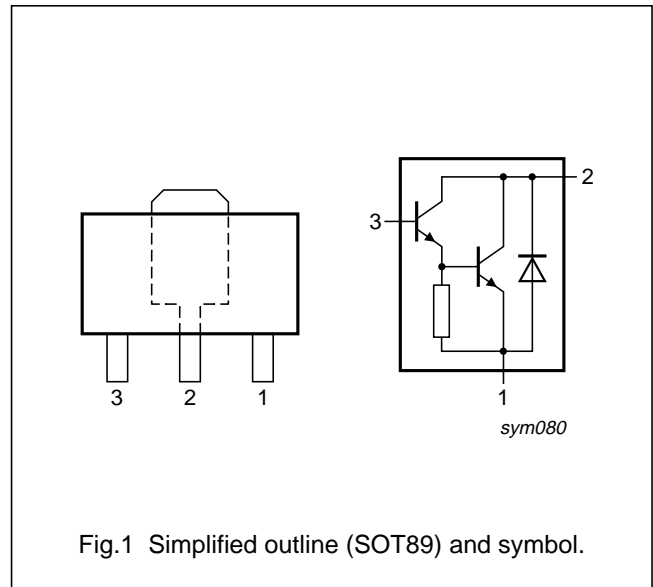
NPN Darlington transistor in a SOT89 plastic package.
PNP complements: BST60, BST61 and BST62.

MARKING

TYPE NUMBER	MARKING CODE
BST50	AS1
BST51	AS2
BST52	AS3

PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BST50	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89
BST51			
BST52			

NPN Darlington transistors

BST50; BST51; BST52

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BST50		–	60	V
	BST51		–	80	V
	BST52		–	90	V
V _{CES}	collector-emitter voltage	V _{BE} = 0 V			
	BST50		–	45	V
	BST51		–	60	V
	BST52		–	80	V
V _{EBO}	emitter-base voltage	open collector	–	5	V
I _C	collector current (DC)		–	1	A
I _{CM}	peak collector current		–	2	A
I _B	base current (DC)		–	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	–	1.3	W
T _j	junction temperature		–	150	°C
T _{amb}	ambient temperature		–65	+150	°C
T _{stg}	storage temperature		–65	+150	°C

Note

- Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm².
For other mounting conditions, see *“Thermal considerations for SOT89 in the General Part of associated Handbook”*.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	96	K/W
R _{th(j-s)}	thermal resistance from junction to soldering point		16	K/W

Note

- Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm².
For other mounting conditions, see *“Thermal considerations for SOT89 in the General Part of associated Handbook”*.

NPN Darlington transistors

BST50; BST51; BST52

CHARACTERISTICS

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

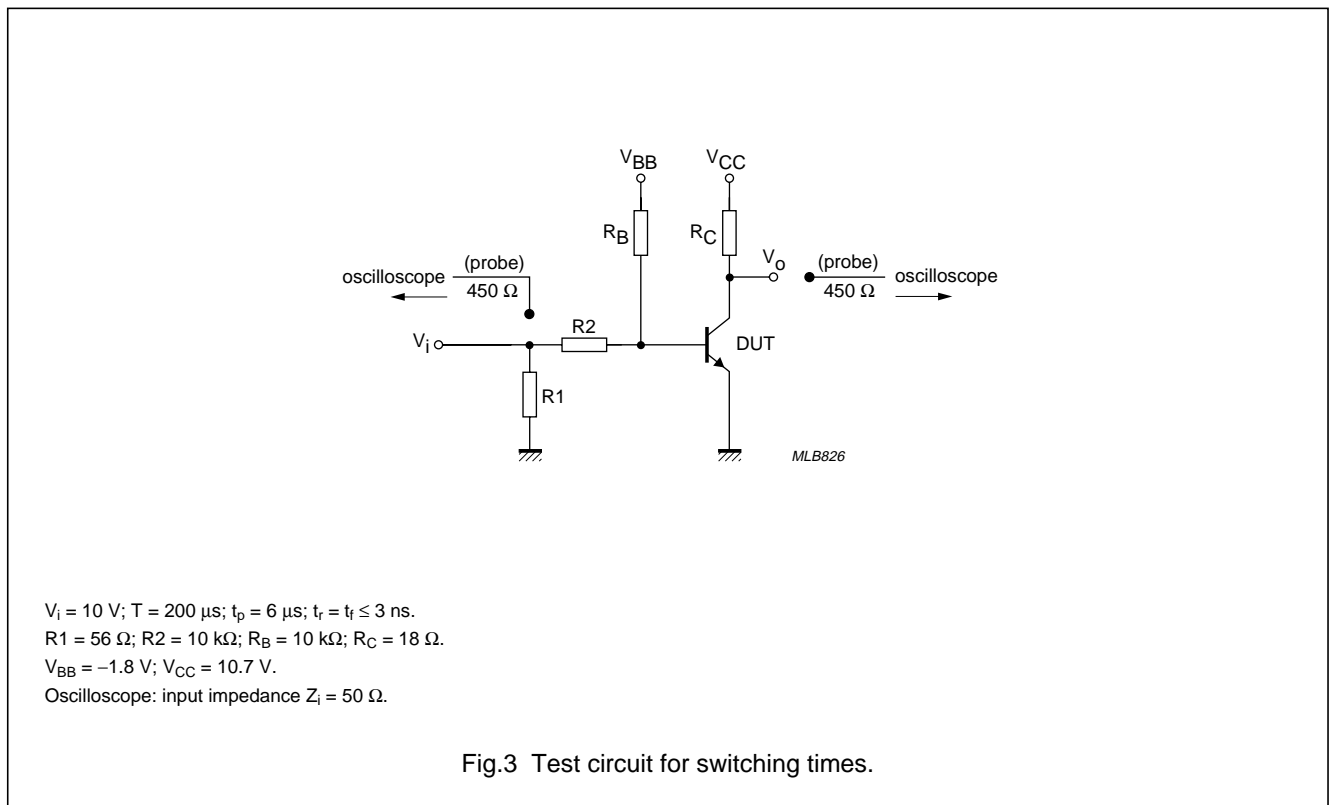
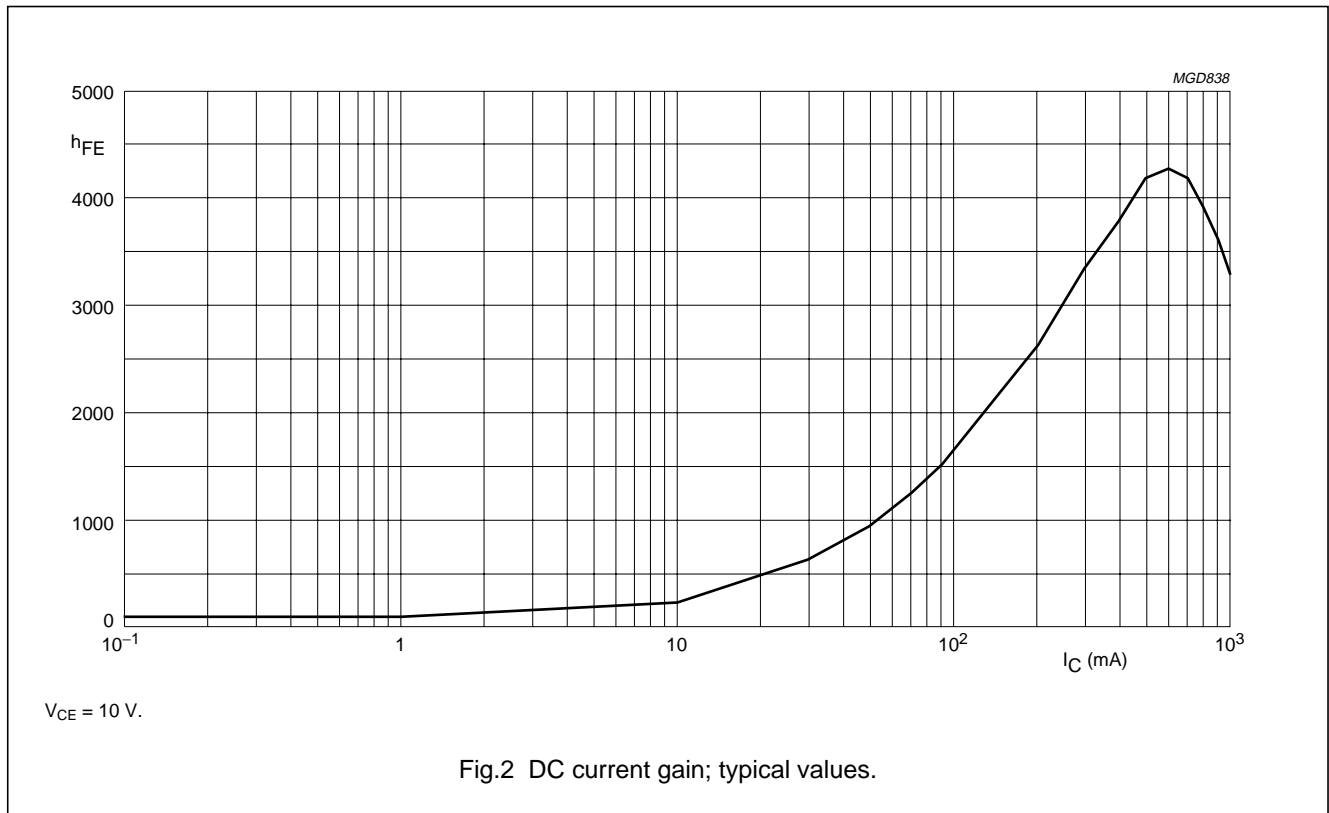
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CES}	collector-emitter cut-off current					
	BST50	$V_{BE} = 0\text{ V}; V_{CE} = 45\text{ V}$	–	–	50	nA
	BST51	$V_{BE} = 0\text{ V}; V_{CE} = 60\text{ V}$	–	–	50	nA
	BST52	$V_{BE} = 0\text{ V}; V_{CE} = 80\text{ V}$	–	–	50	nA
I_{EBO}	emitter-base cut-off current	$I_C = 0\text{ A}; V_{EB} = 4\text{ V}$	–	–	50	nA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}$; note 1; (see Fig.2)				
		$I_C = 150\text{ mA}$	1000	–	–	
		$I_C = 500\text{ mA}$	2000	–	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 500\text{ mA}; I_B = 0.5\text{ mA}$	–	–	1.3	V
		$I_C = 500\text{ mA}; I_B = 0.5\text{ mA}; T_j = 150\text{ °C}$	–	–	1.3	V
V_{BEsat}	base-emitter saturation voltage	$I_C = 500\text{ mA}; I_B = 0.5\text{ mA}$	–	–	1.9	V
f_T	transition frequency	$I_C = 500\text{ mA}; V_{CE} = 5\text{ V}; f = 100\text{ MHz}$	–	200	–	MHz
Switching times (between 10% and 90% levels); (see Fig.3)						
t_{on}	turn-on time	$I_{Con} = 500\text{ mA}; I_{Bon} = 0.5\text{ mA}; I_{Boff} = -0.5\text{ mA}$	–	400	–	ns
t_{off}	turn-off time		–	1500	–	ns

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

NPN Darlington transistors

BST50; BST51; BST52



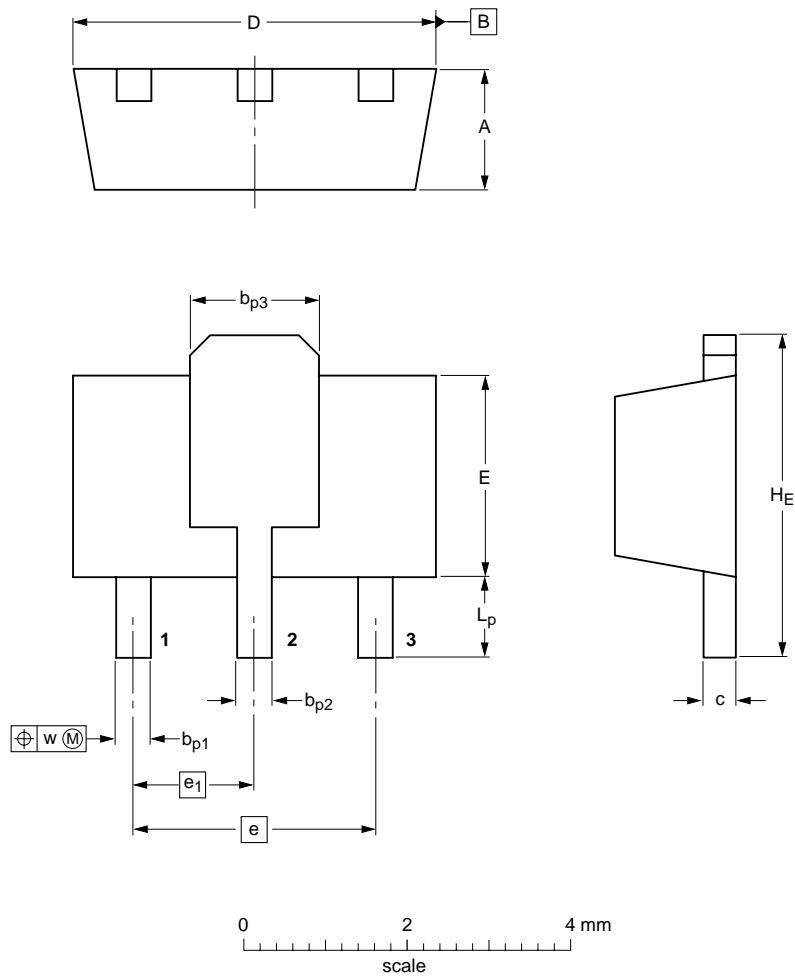
NPN Darlington transistors

BST50; BST51; BST52

PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

SOT89



DIMENSIONS (mm are the original dimensions)

UNIT	A	b _{p1}	b _{p2}	b _{p3}	c	D	E	e	e ₁	H _E	L _p	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.23	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	1.2 0.8	0.13

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT89		TO-243	SC-62		99-09-13 04-08-03

NPN Darlington transistors

BST50; BST51; BST52

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Printed in The Netherlands

R75/05/pp8

Date of release: 2004 Dec 09

Document order number: 9397 750 13877

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